

OVERVIEW

This document describes the differences between industry ethernet communication LSI R-IN32M4-CL2 (CL2) and R-IN32M4-CL3 (CL3), and the precautions when replacing. This document is for users who have developed CC-Link IE Filed Network intelligent device stations or remote device stations using CL2.

The following shows the combinations of the development patterns in replacing CL2 with CL3 and the references.

Operation confirmation device

R-IN32M4-CL3

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1. Overview

This document describes the differences between industry ethernet communication LSI R-IN32M4-CL2 (CL2) and R-IN32M4-CL3 (CL3), and the precautions when replacing. This document is for users who have developed CC-Link IE Field Network intelligent device stations or remote device stations using CL2.

The following shows the combinations of the development patterns in replacing CL2 with CL3 and the references.

Table 1.1 Development patterns

Development	Former LSI	Former development devices	New LSI	New development devices	Note
1	CL2	CC-Link IE Field Intelligent device station/ Remote device station	CL3	CC-Link IE Field Intelligent device station/ Remote device station	Refer to 2.1
2	CL2	CC-Link IE Field Intelligent device station/ Remote device station	CL3	CC-Link IE TSN Remote station	Refer to 2.2

2. Replacement steps

The following is an overview of the replacement procedure.

2.1 Replacement of CL2 (CC-Link IE Field) with CL3 (CC-Link IE Field)

2.1.1 CL2 application circuit change (H/W related)

The differences in communication LSI and changes in cl2 application circuits are described in this article, "3 H/W-Related Differences."

2.1.2 Modify the CL2 sample program (S/W related)

The CL2 sample code (CC-Link IE Field) Cc-Link IE Field communicates the same process, so all user program parts can be diverted.

However, the driver part must be replaced because the h/w-dependent processing is different. Merge user changes, such as OS-related resource settings(kernel_cfg.c).

The differences and diversions of CL2 sample code are described in this article, "Differences between Appendix A CL2(CC-Link IE Field) and CL3 (CC-Link IE Field)."

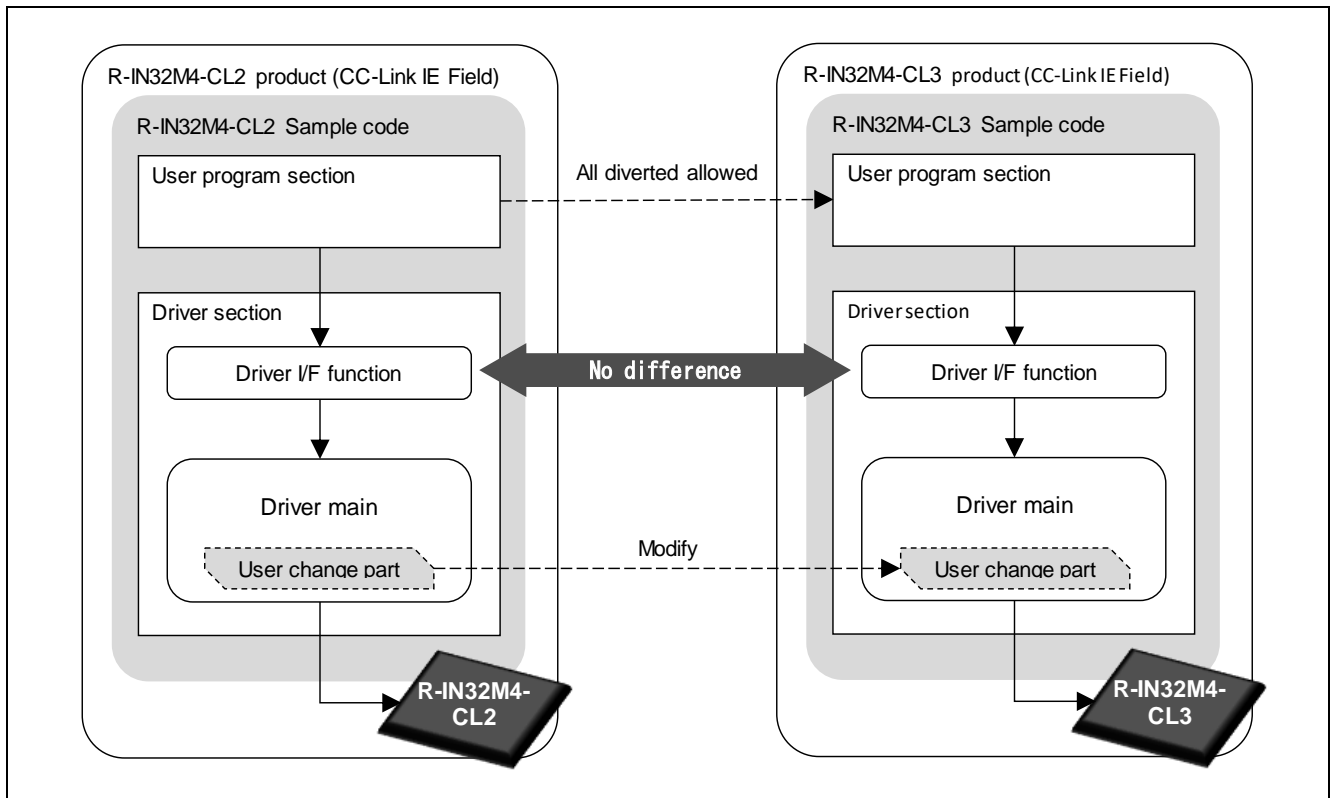


Fig 2.1 Sample program modify and Replacement Image (CC-Link IE Field → CC-Link IE Field)

2.2 Replacement from CL2 (CC-Link IE Field) to CL3 (CC-Link IE TSN)

2.2.1 CL2 application circuit change (H/W related)

The differences in communication LSI and changes in cl2 application circuits are described in this article, "3 H/W-Related Differences."

2.2.2 Modify the CL2 sample program (S/W related)

The CL2 sample code(CC-Link IE Field)describes the communication process of the CC-Link IE Field. Cannot be diverted to CC-Link IE TSN. Both the user program and driver departments need to be replaced.

However, some of the user program parts (user-created processing) can be diverted.

The differences and diversions of CL2 sample code are described in this article, "Differences between Appendix B CL2 (CC-Link IE Field) and CL3 (CC-Link IE TSN)."

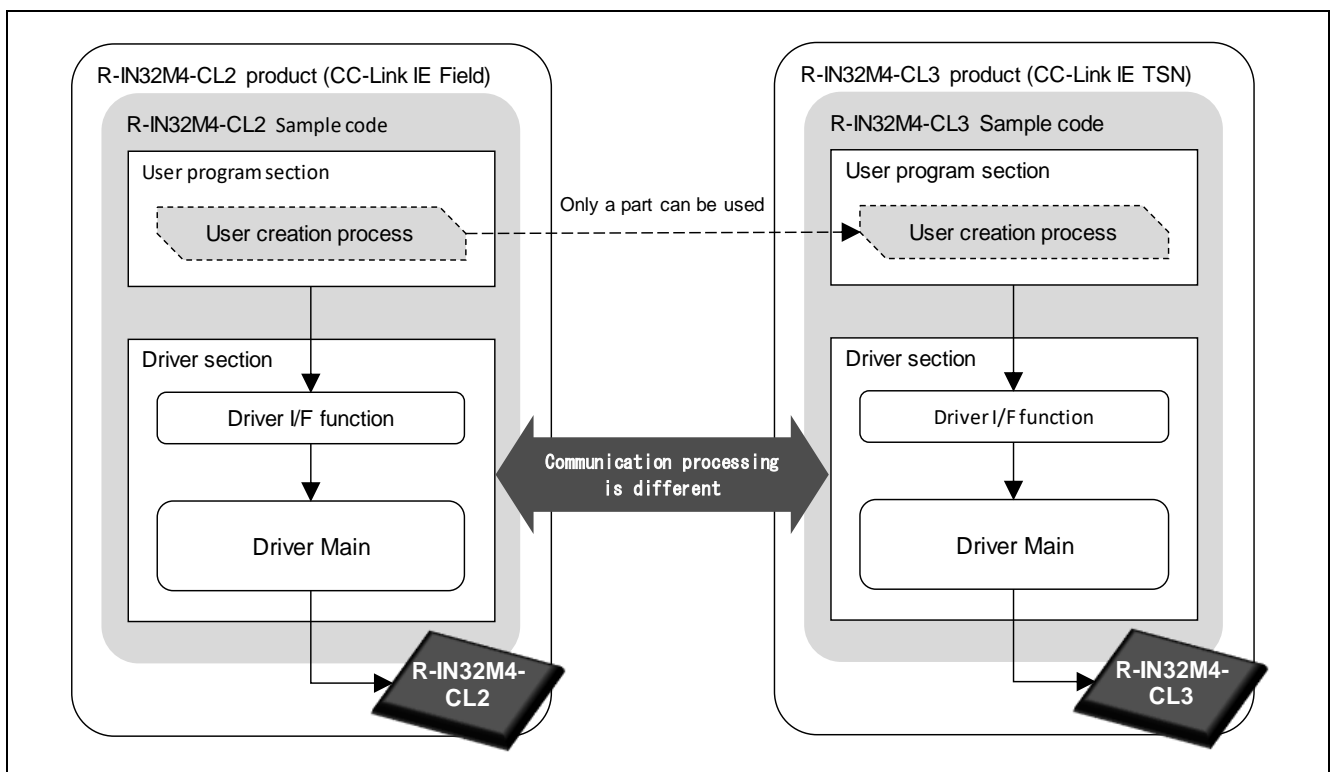


Fig 2.2 Sample program modify and Replacement Image (CC-Link IE Field → CC-Link IE TSN)

3. H/W related differences

CL3 has pin compatibility with CL2, but there are the following differences. In order to replace CL3 on the CL2 board, it is necessary to modify part of the CL2 board. Differences and contents are shown below.

Table 3.1 Differences in specifications when replacing CL2 with CL3

No.	Item	CL2	CL3	CL2 board modification necessity	Reference
1	Power supply voltage	1.0V±0.05V	1.15V±0.06V	Necessity	3.1.1
2	Crystal oscillator input-output (OSC _{TH} =0)	XT1 pin : input XT2 pin : output	XT1 pin : output XT2 pin : input	Necessity	3.1.2
3	2.5V internal regulator	No	Yes	Unnecessity	3.1.3
4	A/D converter	Yes	No	Unnecessity (*)	3.1.4
5	Buffer driving ability	3mA/6mA/9mA	12mA/8mA/10mA	Unnecessity	3.1.5
6	I/O buffer Pull-up/pull-down resistor value	Pull-Up : 50kΩ Pull-down : 50kΩ	Pull-up : 130kΩ Pull-down : 160kΩ	Unnecessity	3.1.6
7	Input buffer type	Normal	Schmitt	Unnecessity	3.1.7
8	2.097152MHz clock	External supply	External supply or Internal generation	Unnecessity	3.1.8
9	Pin differences	—	—	Unnecessity	3.1.9
10	Register differences	—	—	Unnecessity	3.1.10

* : When the AIN[7:0] pins of CL2 are connected to GND or open, no change is required.

3.1 Differences and precautions for replacement

These sections describe hardware-related differences and precautions for replacement.

3.1.1 Power supply voltage

Core voltage in CL3 changes from 1.0V+/-0.05V to 1.15V+/-0.06V. Generate 1.15V+/-0.06V by changing constant of power generation circuit.

3.1.2 Crystal oscillator input-output (OSCTH=0)

When crystal oscillator is used in CL3, input and output of XT1 and XT2 are reversed. Change the resistor position as shown below. Since oscillator circuit characteristics change, the external constant including the existence and the insertion position of the resistor must be revalidated.

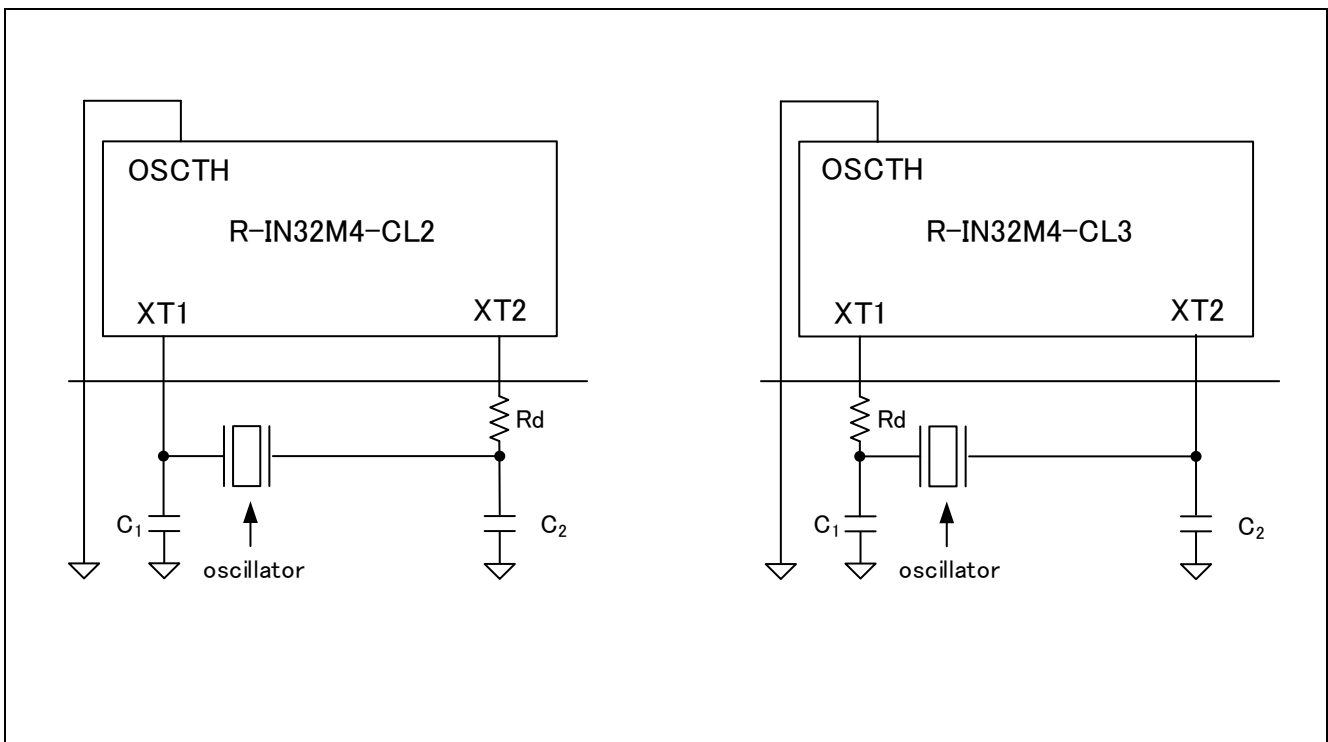


Fig 3.1 CL2, CL3 resistor position

3.1.3 2.5V internal regulator

CL3 has the internal regulator, but when CL3 is replaced on the CL2 board, the external 2.5V supply is used as it is. Thus, there is no need to modify the CL2 board.

3.1.4 A/D converter

Although CL2 has A/D converter, CL3 doesn't have it. Connect the AIN[7:0] pins of CL2 to GND or leave them open.

3.1.5 Buffer driving ability

In CL3, the pin driving ability has been changed as follows.

Table 3.1.5 Buffer driving ability

Target pins	CL2	CL3
PHY0_LED0、PHY1_LED0	3mA	12mA
CSZ0、RDZ、WRSTBZ、WRZ0、WRZ1、RSTOUTZ、 A2-A20、D0-D15、 P00-P07、P10-P17、P20-P27、P30-P37、P40-P47、P50- P52、P57、P60-P67、P70-P77、 RP00-RP07、RP10-RP17、RP20-RP27、RP30-RP37、 EXTP0-EXTP9、 TRACECLK、TRACEDATA0-TRACEDATA3、TMS、TDO	6mA	8mA
BUSCLK	9mA	10mA

3.1.6 I/O buffer Pull-up/pull-down resistor value

In CL3, the I/O buffer pull-up/pull-down resistor value has been changed as follow.

Table 3.1.6 I/O buffer pull-up/pull-down resistor value

Pull-up/Pull-down	CL2	CL3
Pull-up resistor	50kΩ	130kΩ
Pull-down resistor	50kΩ	160kΩ

3.1.7 Buffer type

In CL3, the input buffer type has been changed as follows.

Table 3.1.7 Input buffer type

Target pins	CL2	CL3
P20-P23、P25-P27、P30- P33、P44、P53-P56、P60- P67、 RP00-RP04、RP20-RP27	Normal input	Schmitt input

3.1.8 2.097152MHz clock

CL3 can select 2.097152MHz clock with the CLK2MSEL pin, but when CL3 is replaced on the CL2 board, the external 2.097152MHz clock is selected as it is. Thus, there is no need to modify the CL2 board.

3.1.9 Pin differences

In CL3, the following pins have been changed as follows. there is no need to modify the CL2 board. (No.1 needs to be confirmed)

Table 3.1.9 Pin differences

No	CL2	CL3	Pin position	Remarks
1	AIN[7:0]	GND/OPEN	J22, J21, K22, K21, L22, L21, L20, L19	Refer to 3.1.4 When the AIN[7:0] are connected to GND or leave them open, there is no need to modify board.
2	AVREFFP	VDD33	K20	—
3	AVREFM	GND	J20	—
4	AVDD	VDD33	K19	—
5	AGND	GND	J19	—
7	TEST1 : Renesas test pin (GND connection)	GND	U6	—
8	TEST2 : Renesas test pin (OPEN)	GND/OPEN	L10	—
9	TMC1 : Renesas test pin(GND connection)	CLK2MSEL : 2MHz clock selection 0 : CCI_CLK2_097M 1 : internal generated clock	R19	Refer to 3.1.8
10	TMC2 : Renesas test pin(GND connection)	TEST7 : Renesas test pin (GND connection)	P19	—
11	GND	REG_EN	E6	—
12	GND	AGND	E5, E4	—
13	GND	AVDDREG_33	G6	—
14	GND	VDDREG_33	G5	—
15	GND	REG_OUT	F4	—
16	GND	REG_FB	H4	—
17	VDD33_GPHY	VDD33	J9, J8, K9, L9, M9, N9, P9, P8	—
18	VDD10	VDD11	H17, H16, H15, H14, H13, J17, J13, J7, J6, K17, K13, L17, L13, M17, M13, N17, N13, P18, P17, P13, P7, P6, R17, R16, R15, R14, R13	—
19	VDD1A	VDD11A	K3, L3	—

3.1.10 Register differences

In CL3, the following registers of CC-Link, A/D converter and Motor control (TAPA/PIC) are removed from CL2. In addition, the following registers cannot be used. Do not write access these addresses and use the default values.

Table 3.1.10 Register Differences

Register Name	Symbol	Address
PHY reset switching register	PHYRSTCH	BASE + 1224H
CC-Link IE Field Clock Gate Register	CIECLKGTD	BASE + 0938H
SRAM Bridge Select Register	SRAMBRSEL	BASE + 0804H
TOUTD output stop control register	STOP_TOUTD	BASE + 1260H
TOUTD output select register	TOUTD_SEL	BASE + 1264H
Error detection signal select register 0	ERRDETSEL0	BASE + 1268H
Error detection signal select register 1	ERRDETSEL1	BASE + 126CH

Appendix

S/W Related Differences

A Difference between CL2 (CC-Link IE Field) and CL3 (CC-Link IE Field)

In replacing CL2(CC-Link IEField) to CL3(CC-Link IEField), Shows the differences between S/W-related (sample code) and diversion.

A-1 Differences in user program part

There is no difference in the user program part. All user program parts of the CL2 sample code can be diverted to CL3.

A-2 Driver part differences

The driver part is different from the driver interface function and the driver callback function, but there is a difference in the driver body.

The change file of the driver part, the contents of the change, and the reason are shown below.

Table A.1 Definition of change reason number

Number	Definition
1	It is a change of S/W definition and control with h/w change to CL3 such as ports and registers.
2	It is a change by the difference of the development environment.
3	Other (review and refactoring) changes.

Table A.2 Change file

No.	Folder under (root) ¥ Device ¥ Renesas ¥ RIN32M4	File name	What's changed	Change Reason
1	Include	RIN32M4_CL3.h *1 (Before change RIN32M4.h)	Interrupt, change register definition	1, 3
2	Source¥Project¥TS-R-IN32M4-CL3 (TS-R-IN32M4-CL2 before change)	board_init.c	Port initialization, change control	1
3		board_init.h		
-	cie_intelligent_device also cie_remote_device	-	-	-
4	IAR	main_jp.ewp	Changing target devices Setting change due to IAR EWARM version up	1, 2
5	root	kernel_cfg.c	Stack resizing of main task	3
6		main.c	Adding and changing CC-Link IE-related register control	1
7	root¥Japanese¥driver¥src	R_IN32D_reg.c		
8	also root¥English¥driver¥src	R_IN32D_led.c	Add or change LED-related register control	1
9		R_IN32M4_0.h		
10		R_IN32M4_1.h		

- *1) The contents that were defined in RIN32M4.h in CL2 are renamed in RIN32M4_CL3.h, with the file name changed in CL3. However, by including RIN32M4_CL3.h in RIN32M4.h, there is no change in the header file name to be included in the C file.

B Difference between CL2 (CC-Link IE Field) and CL3 (CC-Link IE TSN)

In replacing CL2(CC-Link IEField) to CL3(CC-Link IE TSN), Shows the differences between S/W-related (sample code) and diversion.

B-1 Differences in user program part

Indicates the difference and compatibility of the user program part. In addition, it shows the precautions at the time of the diversion.

Table B.1 Definition of compatibility symbol

Compati bility	Definition
○	The processing in the function is the same as before. (Variable prefixes and subroutine prefixes in functions are different from conventional ones.) It can be diverted as it is.
△	The processing in the function is different from the past (The function function and purpose are the same, but the processing in the function is different.) Review the contents of the function described in Chapter 5 of "Creating a User Program" in "R-IN32M4-CL3 User's Manual CC-Link IE TSN" to determine whether it can be diverted and consider alternative processing if necessary.
×1	It's a newly created function that's not new. Review the contents of the appropriate function described in Chapter 5 of "Creating a User Program" in "R-IN32M4-CL3 User's Manual CC-Link IE TSN" and implement the new processing as needed.
×2	This is a function that was previously removed. Cc-Link IE TSN is a feature you don't need.

Table B.2 Initial related

No.	Project (Processing described in CL2)	CL2 function name	CL3 function name	Compa tibility
1	Main processing *1	iUserMainRoutine	Main processing per task	×1
2	Initialization process *2	iUserInitialization	iUserInitialization	△
3	Communication start processing	iUserStart	iUserStart	○

*1) Distribute "User application main process" in iUserMainRoutine to main process in each task.

*2) Use user processing (processing to obtain the H / W switch value on the CL2 application circuit) for CL3 IP address setting.

Table B.3 Cyclic transmission processing related

No.	Project (Processing described in CL2)	CL2 function name	CL3 function name	Compa tibility
1	Cyclic transmission stop processing	UserStopCyclic	No corresponding function	×2
2	MyStatus from master bureau and cyclic reception Processing* ¹	UserReceiveCyclic	UserReceiveCyclic	△
3	MyStatus send process	UserSendMyStatus	UserSendNodeStatus	○
4	Cyclic send process	UserSendCyclic	UserSendCyclic	△
5	Communication state update process	UserUpdateStatus	UserUpdateStatus	○
6	Cyclic Transmission Status Update Processing	UserGetCyclicStatus	UserGetCyclicStatus	○
7	Token frame reception process addressed to your station	iUserMyStaRcvTkn	No corresponding function	×2

※1 When porting Hold / Clear processing, note that the processing for determining whether there is an error in the master station is different.

Table B.4 State Management Related

No.	Project (Processing described in CL2)	CL2 function name	CL3 function name	Compa tibility
1	Self-station error handling	UserForceStop	UserForceStop	△
2	Event Handling	iUserExecuteMain	iUserExecuteMain	△
3	LED update processing	UserUpdateLed	UserUpdateLed	○
4	MIB information retrieval process	UserGetMIB	UserGetMIB	○

Table B.5 Transient transmission (1)

No.	Project (Processing described in CL2)	CL2 function name	CL3 function name	Compa tibility
Send and receive main related				
1	Transient1、Transient2、TransientAck Receive processing	UserReceiveTransient	UserSlmpReceive	×1
2	Transient1、Transient2、TransientAck Receive processing	UserSendTransient	UserSendSlmp	×1
Transient1-SLMP-related				
3	SLMP Memory Read Request Frame Receive Response Processing	erUserHandleReceivedMemReadRequest	erUserSlmpReceiveMemoryReadRequest	△
4	SLMP Memory Write Request Frame Receive Response Processing	erUserHandleReceivedMemWriteRequest	erUserSlmpReceiveMemoryWriteRequest	△
5	SLMP Memory Read Request Frame Creation Process	erUserSetSlmpMemReadRequest	iUserSlmpMakeMemoryReadRequest	△

6	SLMP Memory Read Response Frame Receive Processing	erUserHandleReceivedMemReadResponse	UserSlmpReceiveMemoryReadResponse	○
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Table B.6 Transient transmission (2)

No.	Project (Processing described in CL2)	CL2 function name	CL3 function name	Compatibility
Transient1 (CC-Link IE Field specific) related				
1	Transient1 Received Data Processing	UserHandleReceivedTransient1	No corresponding function	×2
2	Transient1 Received Data Assembly Start Processing	UserStartMakingReceivedTransient1	Ditto	×2
3	Transient1 Received Data Assembly	blUserMakeReceivedTransient1	Ditto	×2
Transient2 Related				
4	Transient2 Received Data Processing	UserHandleReceivedTransient2	No corresponding function	×2
5	Transient2 Receive Data Check Processing	erUserCheckReceivedTransient2	Ditto	×2
6	Transient2 Memory Write Request Receive Processing	erUserHandleReceivedTransient2_RequestSetMemory	Ditto	×2
7	Transient2 Response Frame Creation Process	ulUserSetTransient2_Response	Ditto	×2
8	Transient2 Request Frame Creation Process	UserSetTransient2_Request	Ditto	×2
9	Transient2 Memory Read Request Frame Creation Process	ulUserSetTransient2_RequestGetMemory	Ditto	×2
10	Transient2 Memory Read Response Receive Processing	erUserHandleReceivedTransient2_ResponseGetMemory	Ditto	×2
TransientAck Related				
11	TransientAck Received Data Processing	UserHandleReceivedTransientAck	No corresponding function	×2
12	TransientAck frame creation process	blUserSetTransientAck	Ditto	×2

Note) The frames used for transient transmission differ in the CC-Link IE field network and the CC-Link IE TSN. Therefore, the above frame-related processing (except SLMP) described in the CL2 sample code is not in the CL3 sample code.

The CC-Link IE field network uses Transient1 (Field-specific commands), Transient1 (SLMP), Transient2, and TransientAck. The CC-Link IE TSN uses SLMP.

B-2 Driver part differences

The driver part differs from the driver interface function, the driver callback function, and the driver body.

The driver part of the CL2 sample code cannot be diverted to CL3. Use the CL3 driver described for CL3 to develop CC-Link IE TSN-enabled product.

Revision History

Rev.	Date	Description	
		Page	Summary
1.00	Nov 18, 2019	—	First edition issued

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity.

Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).

7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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